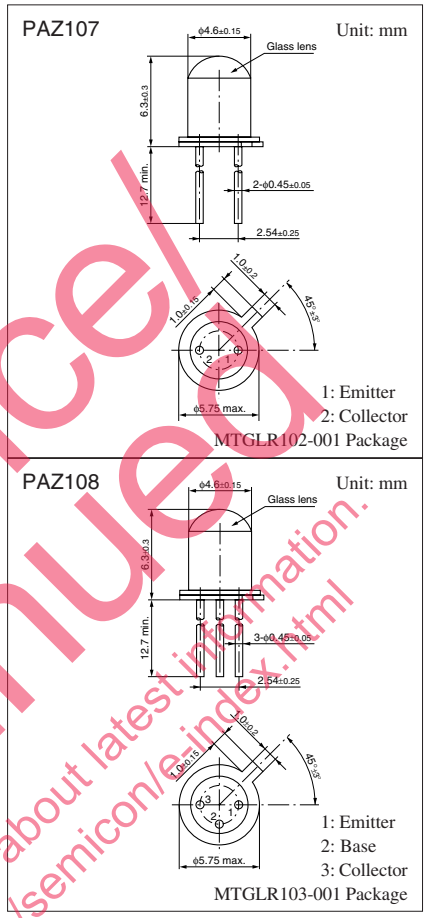
PNZ107 (PN107), PNZ108 (PN108)

Silicon planar type

For optical control systems



■ Features

- High sensitivity: $I_{CE(L)}$ = 5 mA (min.)
- Narrow directivity characteristics for effective use of light input
- Fast response: t_r = 5 µs (typ.)
- Signal mixing capability using base pin (PNZ108)
- TO-18 standard type package

■ Absolute Maximum Ratings T_a = 25°C

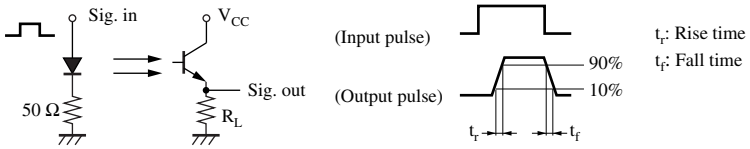
Parameter		Symbol	Rating	Unit
Collector-emitter voltage (Base open)		V_{CEO}	20	V
Collector-base voltage (Emitter open)	PNZ108	V_{CBO}	30	V
Emitter-collector voltage (Base open)		V_{ECO}	3	V
Emitter-base voltage (Collector open)	PNZ108	V_{EBO}	5	V
Collector current		I_C	30	mA
Collector power dissipation *		P_C	150	mW
Operating ambient temperature		T_{opr}	−25 to +85	°C
Storage temperature		T_{stg}	−30 to +100	°C

Note) *: The rate of electric power reduction is 1.5 mW/°C above T_a = 25°C.

■ Electrical Characteristics T_a = 25°C ± 3°C

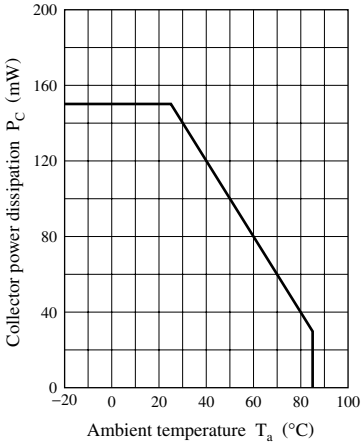
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Photocurrent *1	$I_{CE(L)}$	V_{CE} = 10 V, L = 100 lx	5.0		15.0	mA
Dark current	I_{CEO}	V_{CE} = 10 V		0.05	2.00	µA
Peak emission wavelength	λ_p	V_{CE} = 10 V		900		nm
Half-power angle	θ	The angle from which photocurrent becomes 50%		10		°
Rise time *2	t_r	V_{CC} = 10 V, $I_{CE(L)}$ = 5 mA, R_L = 100 Ω		5		µs
Fall time *2	t_f			6		µs
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_{CE(L)}$ = 1 mA, L = 500 lx		0.3	0.6	V

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.
3. This device is designed be disregarded radiation.
4. *1: Source: Tungsten (color temperature 2 856 K)
*2: Switching time measurement circuit

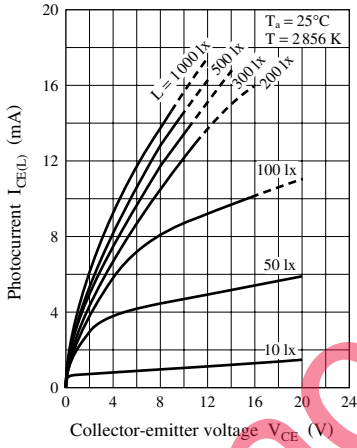


Note) The part numbers in the parenthesis show conventional part number.

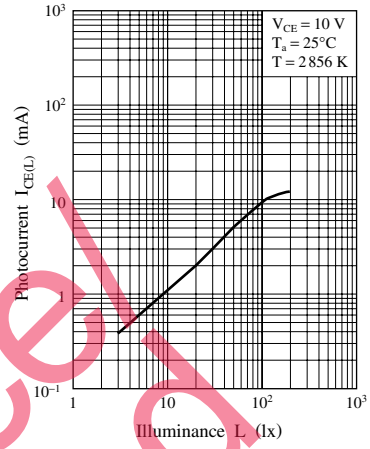
P_C — T_a



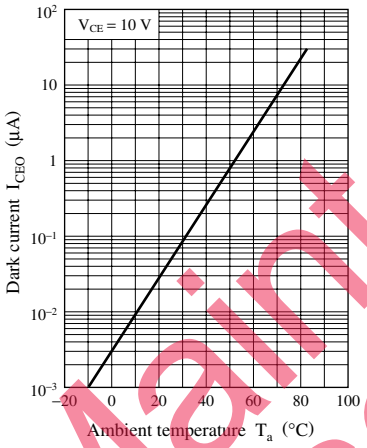
$I_{CE(L)}$ — V_{CE}



$I_{CE(L)}$ — L

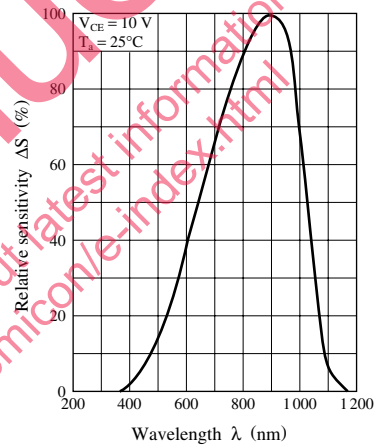


I_{CEO} — T_a

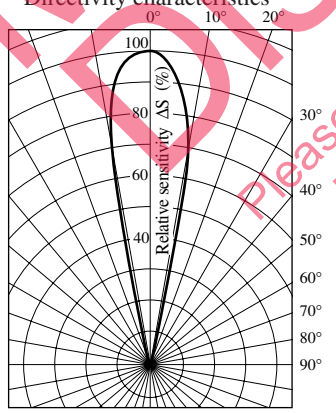


$I_{CE(L)}$ — T_a

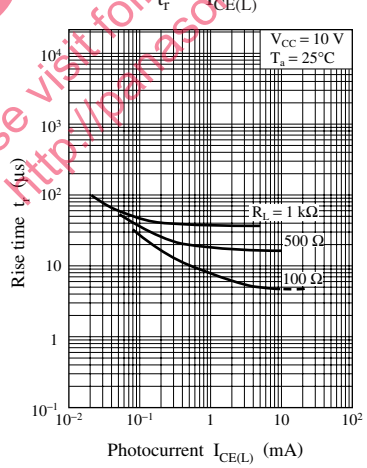
Spectral sensitivity characteristics



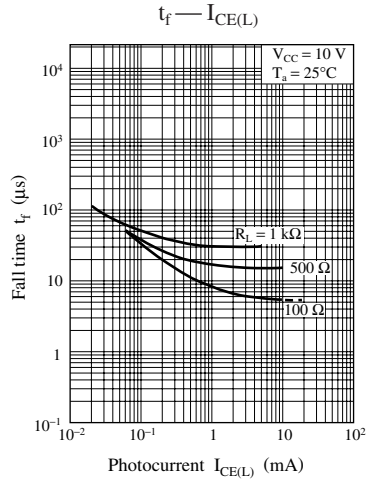
Directivity characteristics



t_r — $I_{CE(L)}$



t_f — $I_{CE(L)}$



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